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HMC349MS8G / 349MS8GE



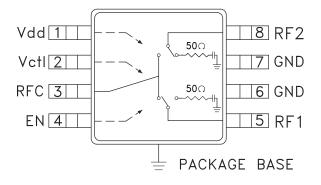
HIGH ISOLATION SPDT NON-REFLECTIVE SWITCH, DC - 4 GHz

Typical Applications

The HMC349MS8G / HMC349MS8GE is ideal for:

- Basestation Infrastructure
- MMDS & 3.5 GHz WLL
- CATV/CMTS
- Test Instrumentation

Functional Diagram



Features

High Isolation: 70 dB @ 1 GHz

57 dB @ 2 GHz

Single Positive Control: 0/+5V

+52 dBm Input IP3

Non-Reflective Design

All Off State

Ultra Small MS8G SMT Package: 14.8 mm² Included in the HMC-DK005 Designer's Kit

General Description

The HMC349MS8G & HMC349MS8GE are high isolation non-reflective DC to 4 GHz GaAs MESFET SPDT switches in low cost 8 lead MSOP8G surface mount packages with exposed ground paddles. The switch is ideal for cellular/PCS/3G basestation applications yielding 50 to 60 dB isolation, low 0.8 dB insertion loss and +52 dBm input IP3. Power handling is excellent up through the 3.5 GHz WLL band with the switch offering a P1dB compression point of +31 dBm. On-chip circuitry allows a single positive voltage control of 0/+5 Volts at very low DC currents. An enable input (EN) set to logic high will put the switch in an "all off" state.

Electrical Specifications, $T_{\Delta} = +25^{\circ}$ C, Vctl = 0/+5 Vdc, Vdd = +5 Vdc, 50 Ohm System

Parameter	Frequency	Min.	Тур.	Max.	Units
Insertion Loss	DC - 1.0 GHz DC - 2.0 GHz DC - 3.0 GHz DC - 4.0 GHz		0.8 0.9 1.2 1.8	1.1 1.2 1.5 2.1	dB dB dB dB
Isolation (RFC to RF1/RF2)	DC - 1.0 GHz DC - 2.0 GHz DC - 3.0 GHz DC - 4.0 GHz	60 54 45 42	70 57 50 47		dB dB dB dB
Return Loss (On State)	DC - 1.0 GHz DC - 2.0 GHz DC - 3.0 GHz DC - 4.0 GHz		23 18 13 8		dB dB dB dB
Return Loss (Off State)	0.5 - 2.0 GHz 0.5 - 3.0 GHz 0.5 - 4.0 GHz		20 17 14		dB dB dB
Input Power for 1 dB Compression	0.25 - 4.0 GHz	27	31		dBm
Input Third Order Intercept (Two-Tone Input Power = +7 dBm Each Tone)	0.25 - 1.0 GHz 1.0 - 2.0 GHz 2.0 - 3.0 GHz 3.0 - 4.0 GHz		53 50 49 47		dBm dBm dBm dBm
Switching Speed	DC - 4.0 GHz				
tRISE, tFALL (10/90% RF) tON, tOFF (50% CTL to 10/90% RF)			40 120		ns ns

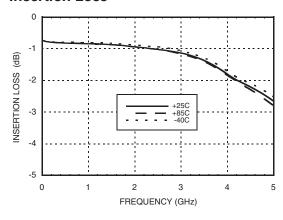
HICROWAVE CORPORATION

HMC349MS8G / 349MS8GE

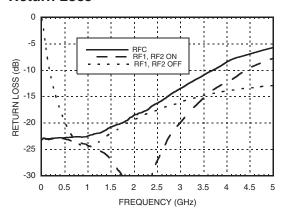


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Insertion Loss

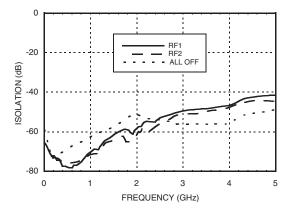


Return Loss

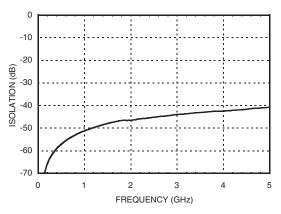


Note: RFC is reflective in "all off" state.

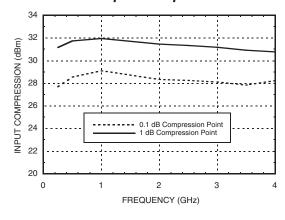
Isolation Between Ports RFC and RF1 / RF2



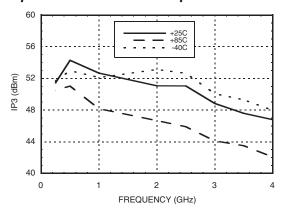
Isolation Between Ports RF1 and RF2



0.1 and 1 dB Input Compression Point



Input Third Order Intercept Point





HIGH ISOLATION SPDT **NON-REFLECTIVE SWITCH, DC - 4 GHz**



Absolute Maximum Ratings

	_	
RF Input Power (VctI = 0V/+5V) (0.25 - 4 GHz)	+30 dBm (T = +85 °C)	
Supply Voltage Range (Vdd)	+7 Vdc	
Control Voltage Range (Vctl)	-1V to Vdd +1V	
Hot Switch Power Level (Vdd = +5V)	+30 dBm	
Channel Temperature	150 °C	
Continuous Pdiss (T = 85 °C) (derate 12 mW/°C above 85 °C)	0.75 W	
Thermal Resistance	87 °C/W	
Storage Temperature	-65 to +150 °C	
Operating Temperature	-40 to +85 °C	
ESD Sensitivity (HBM)	Class 1A	

Note: DC blocking capacitors are required at ports RFC, RF1 and RF2. Their value will determine the lowest transmission frequency.



Bias Voltage & Current

Vdd Range = +5.0 Vdc ± 10%			
Vdd (Vdc)	Idd (Typ.) (mA)	ldd (Max.) (mA)	
+5.0	2.3	5.0	

TTL/CMOS Control Voltages

State	Bias Condition	
Low 0 to +0.8 Vdc @ <1 µA Typical		
High	+2.0 to +5.0 Vdc @ 30 μA Typical	

Truth Table

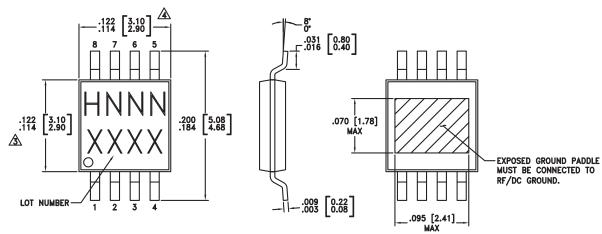
Control Input		Signal Path State		
Vctl	EN	RFC - RF1	RFC - RF2	
Low	Low	OFF	ON	
High	Low	ON	OFF	
Low	High	OFF	OFF	
High	High	OFF	OFF	

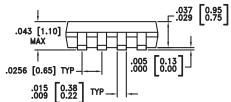




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Outline Drawing





NOTES:

- 1. LEADFRAME MATERIAL: COPPER ALLOY
- 2. DIMENSIONS ARE IN INCHES [MILLIMETERS]
- DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.15mm PER SIDE.
- DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.25mm PER SIDE.
- 5. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.

Package Information

Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking [3]
HMC349MS8G	Low Stress Injection Molded Plastic	Sn/Pb Solder	MSL1 [1]	H349 XXXX
HMC349MS8GE	RoHS-compliant Low Stress Injection Molded Plastic	100% matte Sn	MSL1 [2]	<u>H349</u> XXXX

- [1] Max peak reflow temperature of 235 °C
- [2] Max peak reflow temperature of 260 °C
- [3] 4-Digit lot number XXXX



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Pin Descriptions

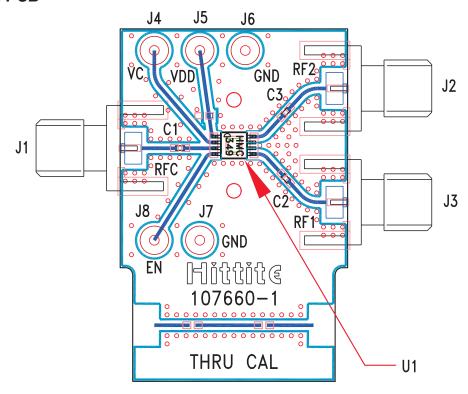
Pin Number	Function	Description	Interface Schematic
1	Vdd	Supply Voltage.	
2	Vctl	Control input. See truth and control voltage tables.	Vctl 134K 500 =
3, 5, 8	RFC, RF1, RF2	These pins are DC coupled and matched to 50 Ohms. Blocking capacitors are required.	
4	EN	Enable. See truth and control voltage tables.	Vctl 134K
6, 7	GND	Package bottom must also be connected to PCB RF ground.	GND =





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Evaluation PCB



List of Materials for Evaluation PCB 107662 [1]

Item	Description
J1 - J3	PCB Mount SMA RF Connector
J4 - J8	DC Pin
C1 - C3	100 pF Capacitor, 0402 Pkg.
U1	HMC349MS8G / HMC349MS8GE SPDT Switch
PCB [2]	107660 Evaluation PCB

^[1] Reference this number when ordering complete evaluation PCB

The circuit board used in the final application should be generated with proper RF circuit design techniques. Signal lines at the RF port should have 50 ohm impedance and the package ground leads and backside ground slug should be connected directly to the ground plane similar to that shown above. The evaluation circuit board shown above is available from Hittite Microwave Corporation upon request.

^[2] Circuit Board Material: Rogers 4350